

Amendments To The Specification

Please replace the paragraph in the specification page 9, line 17 to page 10, line 3 with the following amended paragraph:

The central region **406** has a plurality of ball lands **420 (not shown)**, and these ball lands receives the solder balls of the lower semiconductor package (not shown) stacked above the printed circuit board **400** for electrical connection. The ball lands **420 (not shown)** in the central region **406** are also electrically connected to the pads **402** by a circuit pattern (not shown) of the printed circuit board **400**. The PCB circuit pattern (not shown) is predetermined according to the connection relationship between the terminals of the upper semiconductor package (not shown) and the lower semiconductor package (not shown). This PCB circuit pattern is made from copper (Cu) or other similar conductive materials.

Please replace the paragraph in the specification page 11, lines 14-25 with the following amended paragraph:

As shown in **FIGS. 6A-6B**, a first semiconductor package **604** (for example, a BGA package) is mounted on the upper surface of a printed circuit board **602**. The first semiconductor package **604** has a lower surface having a plurality of solder balls **610**. In the similar manner as already described above with respect to **FIG. 4**, the central region of the printed circuit board **602** has a plurality of ball lands **620 (not shown)**. The solder balls **610** of the first semiconductor package **604** are electrically connected to the ball lands **620 (not**

~~shown~~) of the printed circuit board **602**. On the lower surface of the printed circuit board **602**, a plurality of ball lands **620** (~~not shown~~) are also formed, and more about this aspect is described below with respect to **FIG. 6C**.

Please replace the paragraph in the specification page 13, lines 3-12 with the following amended paragraph:

According to an embodiment of the present invention, the solder balls 610, 612 and 616 include tin (Sn) as the main material and may also additionally include lead, (Pb), silver (Ag), **1) indium (In), bismuth (Bi), gold (Au), zinc (Zn), copper (Cu)** or antimony (Sb), which is selectively added to **2) one or any combination**. Preferably, the size of each of the solder balls 610, 612, and 616 is set in a range about 100 μm to about 1 mm. Nevertheless, it would be well known to those skilled in the art that other conductive materials can be used instead to form the solder balls of the same or other sizes.

Please replace the paragraph in the specification page 13, lines 23 to page 14, line 5 with the following amended paragraph:

According to a presently preferred embodiment of the present invention, a conductive bump (not shown) can be formed on the pads 614 to secure a connection between the lead frame 608 and the pads 614. The conductive bump (not shown) may be made from any electrically conductive material, such as and preferably Au or Ni. The size of the conductive bump (not shown) is determined

based on the size of the pad 614 and the height of the conductive bump is in the range of about 1 μm to about 100 μm .

Please replace the paragraph in the specification page 15, line 16 to page 16, line 2 with the following amended paragraph:

Instead of the lead frames **608** and **708** as shown and described in the embodiments above with respect to **FIGS. 6A-6C** and **7**, a conventional tape automated bonding tape **800** (hereinafter, "the TAB tape") can be used as the conductive frame to provide electrical connection as shown in FIG 8. Thus, the second semiconductor device **606** or **704** can be electrically connected to the corresponding first semiconductor device **604** or **702** and to the corresponding printed circuit board **602** or **710** by means of the TAB tape **800** ~~(not shown)~~. ~~Although not shown in a drawing, the~~ The TAB tape **800** would adhere to other the components such as the lower surface of the corresponding second semiconductor device **606** or **704** and make an electrical connection.

Please replace the paragraph in the specification page 16, lines 3-10 with the following amended paragraph:

To accomplish this, the TAB tape has an adhesive portion made from an adhesive material of one (or any combination) of an epoxy-based thermoplastic resin, an adhesive glass, and/or an adhesive tape. If the adhesive tape is used as the adhesive material, the thickness of the adhesive tape is in the range about

10 μm to about 100 μm , and a polymer having superior insulation characteristics is used as the material for the adhesive tape.